

Change of IC/LSI package outline

1960s Era of non-fixed lead assembly

Age of TOP

TOP: Transistor Outline Package

1970s Era of pin insertion assembly

Age of DIP

DIP: Dual In-line Package

1980s Era of Surface mount assembly

Age of QFP

QFP: Quad Flat Package

1990s Era of small outline surface assembly

Age of CSP

CŠP: Chip Scale Package

2000s Era of 3D stacked assembly

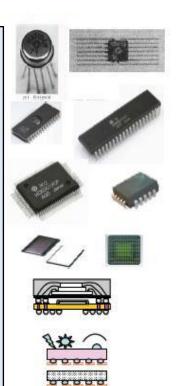
Age of SiP

SiP: System in Package

Era of system assembly after 2010

Age of MiP

MiP: Multi functions in a Package



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